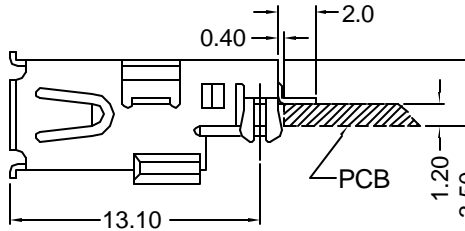
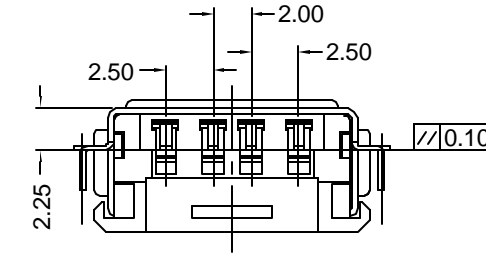


Recommended PCB Layout (Top View)



Material and Finish

Insulator: HTN thermoplastic, UL94V-0 rated, black or white color, Reflow Process Compatible- Recommended Soldering Temperature: 230°C for 30 seconds, 260°C max.

Shield: brass, 0.30mm thick

Shield Finish: 120u" nickel plated over 50u" copper underplate

Contact Material: phosphor bronze

Contact Plating Options:

Standard: gold flash on contact area, 120u" min. tin/lead on soldertails, all over 50u" min. nickel underplate

-30 Option: 30u" gold on contact area, 120u" min. tin/lead on soldertails, all over 50u" min. nickel underplate

Specifications:

- Contact Current Rating: 1A max.
- Contact Resistance: 30 milliohms max.
- Insulation Resistance: 1000 Megohms min.
- Dielectric Withstanding Voltage: 500V AC
- Insertion Force: 3.57kg max.
- Extraction Force: 1.02kg min.
- Operating Temperature: -25°C to +80°C
- Durability: 1500 mating cycles min.

Part Number	Contact Area Plating Finish	Insulator Color	Packaging
KUSBL-SMTAS1NW	Gold Flash (standard)	White	Bulk (trays, standard)
KUSBL-SMTAS1NW30	30u" Gold (30 option)	White	Bulk (trays, standard)
KUSBL-SMTAS1NB	Gold Flash (standard)	Black	Bulk (trays, standard)
KUSBL-SMTAS1NB30	30u" Gold (30 option)	Black	Bulk (trays, standard)
KUSBL-SMTAS1NWTR	Gold Flash (standard)	White	Tape & Reel (TR option)
KUSBL-SMTAS1NW30TR	30u" Gold (30 option)	White	Tape & Reel (TR option)
KUSBL-SMTAS1NBTR	Gold Flash (standard)	Black	Tape & Reel (TR option)
KUSBL-SMTAS1NB30TR	30u" Gold (30 option)	Black	Tape & Reel (TR option)

Tolerances

X.X ± 0.35
X.XX ± 0.25
Unless Stated
Otherwise



REV.	DATE	DESCRIPTION	REV. BY	CHK. BY	DRAWN BY	DATE
A0	1/22/03	New Drawing	T. Gokcek	C. Leiva	T. Gokcek	1/20/03
A1	3/13/03	Release Drawing	T. Gokcek	H. MA		
A2	6/25/04	ECO#04-029	H. MA	C. Leiva		

KUSBL-SMTAS1Nxyzz

x - insulator color
yy - plating option
zz - packaging option

Surface Mount A-Type USB Socket

Low Profile Mount, w/ Tape & Reel Option

